# 3.0A, Synchronous Step-Down DC-DC Converter

# **General Description**

EML3173 is a high efficiency, DC-DC synchronous buck converter witch provides 3.0A output loading after output voltage reach preset voltage. EML3173 regulates the output voltage using Pulse Width Modulation (PWM). The PWM modulation provides low output voltage ripple and fixed frequency noise. Under very heavy load condition, or when the input voltage approaches the output voltage, EML3173 enters low dropout voltage operation under 100% duty cycle.

The internal generated 0.8V precision feedback reference voltage is designed for low output voltage request. Low Power-FET Ron synchronous switch dramatically reduces conduction loss.

The EML3173 is available in an 8-pin, space-saving E-SOP-8L package.

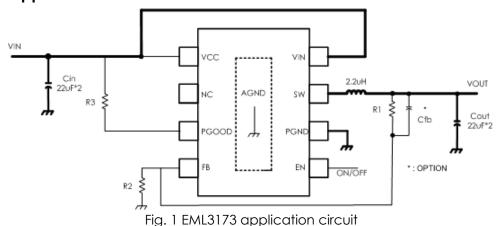
## **Features**

- Wide Operating Voltage Ranges: 2.6V to 5.5V
- 3.0A Output Current
- High efficiency Buck Power Converter
- Pure PWM with lower output ripple
- Power Good Indicator
- LDO mode: duty cycle: 100%
- Synchronous Power Switches Rectification, no Schottky Diode Required
- 1.4MHz Switching Frequency
- Internal Soft-Start
- Current Limit Protection
- Over Temperature Protection
- Output Shorting Protect
- Output Over Voltage Protection

## **Applications**

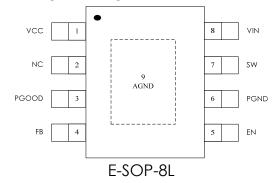
- Cellular telephone
- Wireless and DSL Modems
- Digital Still Cameras
- Portable Products
- MP3 Players

## **Typical Application**



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# **Package Configuration**



## EML3173-00SG08NRR

00 Adjustable

SG08 E-SOP-8L Package

NRR RoHS & Halogen free package

Commercial Grade Temperature

Rating: -40 to 85°C

Package in Tape & Reel

# Order, Mark & Packing information

Package	Vout(V)	Product ID	Marking	Packing
E-SOP-8L	adjustable	EML3173-00SG08NRR	ESMT EML3173 Tracking code  PINI DOT  1 2 3 4	Tape & Reel 3K units

# **Functional Block Diagram**

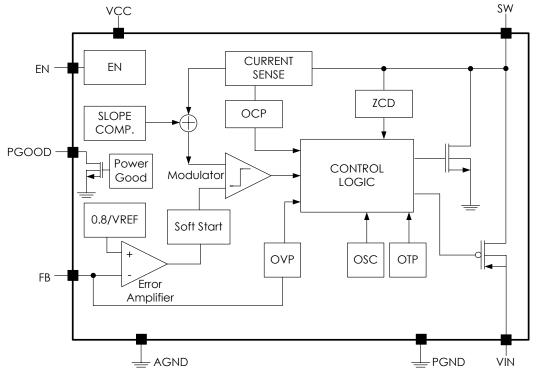


Fig. 2

# **Pin Functions**

Pin Name	E-SOP-8L	Function	
VCC	1	Analog Input Pin.	
VCC	'	Supply power to internal circuit.	
NC	2	Not connected.	
		Power Good Pin	
PGOOD	3	Open-Drain Output. Connect this pin to VCC by a 100K $\Omega$ pull-up	
		resistor.	
		Feedback Pin.	
FB	4	Receives the feedback voltage from an external resistive divider	
		across the output.	
EN 5		Enable Pin.	
		Chip enable pin (1:Enable ; 0:Disable).	
PGND	6	Ground Pin.	
		Switch Pin.	
SW	7	Must be connected to Inductor. This pin connects to the drains of the	
		internal main and synchronous power MOSFET switches.	
		Power Supply Pin.	
VIN	8	Must be closely decoupled to PGND pin with a 22µF*2 or greater	
		ceramic capacitor.	
		Ground Pin/Thermal Pad	
AGND	ND 9	This Pin must be connected to ground. The thermal pad with large	
		thermal land area on the PCB will helpful chip power dissipation.	

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## **Absolute Maximum Ratings**

Devices are subjected to fail if they stay above absolute maximum ratings.

Input Voltage (VIN, VCC)	0.3V to 6.0V
EN, FB Voltages	0.3V to V <sub>IN</sub>
SW Voltage	$ 0.3V$ to $(V_{IN} + 0.3V)$
Lead Temperature (Solder	ing, 10 sec) 260°C

Operating Temperature Range	40°C to 85°C
Junction Temperature (Note 1)	150°C
Storage Temperature Range	65°C to 150°C

## Thermal data

Package	Thermal resistance	Parameter	Value
E COD 01	$\theta$ JA (Note 2)	Junction-ambient	50°C/W
E-SOP-8L	$\theta$ JC (Note 3)	Junction-case	10°C/W

# **Electrical Characteristics**

 $V_{\text{IN}} = V_{\text{VCC}} = V_{\text{EN}} = 3.6 \text{V}, \ V_{\text{OUT}} = 1.2 \text{V}, \ V_{\text{FB}} = 0.8 \text{V}, \ L = 2.2 \text{uH}, \ C_{\text{IN}} = 22 \text{uF*2}, \ C_{\text{OUT}} = 22 \text{uF*2}, \ T_{\text{A}} = 25^{\circ} \text{C}.$ 

Symbol	Parameter	Conditions	Min	Тур	Max	Units
V <sub>IN</sub>	Input Voltage Range		2.6		5.5	٧
1-	Summark (Commark) ( 2 () (	Switching (EN=VCC)		220		μΑ
lq	Supply Current V <sub>IN</sub> =3.6V	Shutdown (EN=0)			1	μΑ
UVLO	Under Voltage Lockout	When SW starts/stops switching	1.8		2.1	<b>V</b>
Vref	Reference Voltage	$V_{IN} = 2.6V \text{ to } 5.0V$	0.784	0.8	0.816	٧
	EN Input Low Voltage	40°0 +05°0			0.4	٧
V <sub>EN</sub>	EN Input High Voltage	-40°C ~ +85°C	1.5			٧
Vo	Output Voltage Range	When using external feedback resistors to drive FB	0.8		VIN	>
Vout	Output Voltage Accuracy	$2.6V \le V_1 \le 5.5V$ , $0mA \le I_0 \le 3A$	0.97xV <sub>NOM</sub>	V <sub>NOM</sub>	1.03xV <sub>NOM</sub>	٧
		$V_{IN} = 2.6V \text{ to } 5.0V, I_{OUT}=10\text{mA}$		0.04		%/V
ΔVουτ/ΔVουτ Line Regulation		V <sub>IN</sub> = 2.6V to 5.0V, I <sub>OUT</sub> =3.0A		0.08		%/V
ΔV <sub>Ουτ</sub> /ΔΙ <sub>Ουτ</sub>	Load Regulation	I <sub>out</sub> = 1mA to 3.0A		0.01		%/A
Ron(P)	R DS(ON) OF PMOS	Iout=100mA		100		mΩ
Ron(n)	R DS(ON) OF NMOS	I <sub>OUT</sub> =100mA		100		mΩ
Іосн	High Side Current Limt	Duty Cycle = 100%, V <sub>IN</sub> = 2.6V to	3.75	4.5	6	Α
locu	Low Side Current Limt	5.0V		-0.6		Α
Fosc	Oscillator Frequency	VFB=0.8V, -40°C ~+85°C	1.12	1.4	1.68	MHz
Max. Duty	Maximum Duty	\\ - 0 (\\ \to 5 0\\	100			%
Min. Duty	Minimum Duty.	$V_{IN} = 2.6V \text{ to } 5.0V$		15		%
OTP	Thermal Shutdown	Hysteresis=35°C		165		$^{\circ}\!\mathbb{C}$

**Note 1:**  $T_J$  is a function of the ambient temperature  $T_A$  and power dissipation  $P_D$  ( $T_J = T_A + (P_D) * \theta_{JA}$ )).

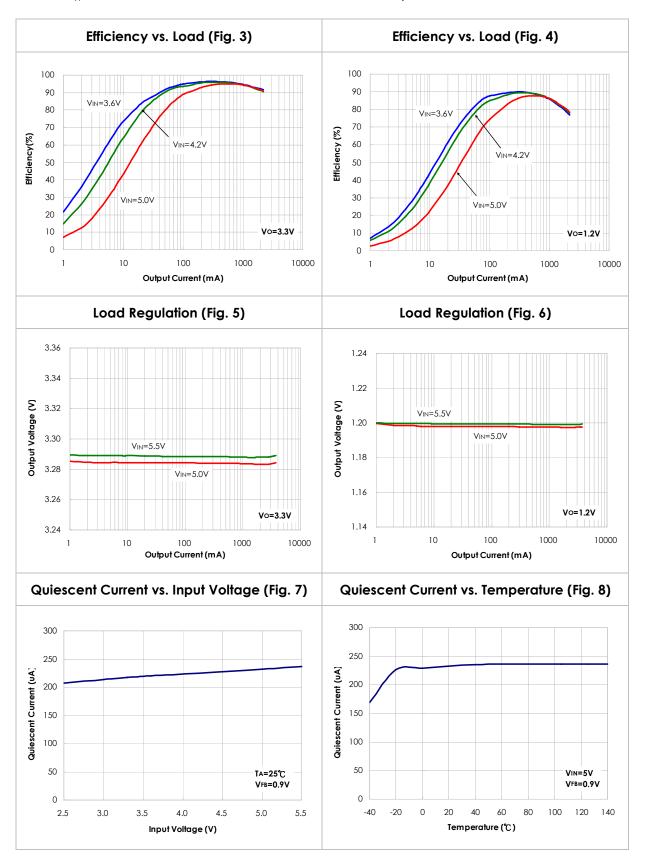
**Note 2:**  $\theta$  JA is measured in the natural convection at TA=25°C on a highly effective thermal conductivity test board(2 layers , 2SOP) according to the JEDEC 51-7 thermal measurement standard.

**Note 3:**  $\theta$  JT represents the heat resistance between the chip and the center of package top.

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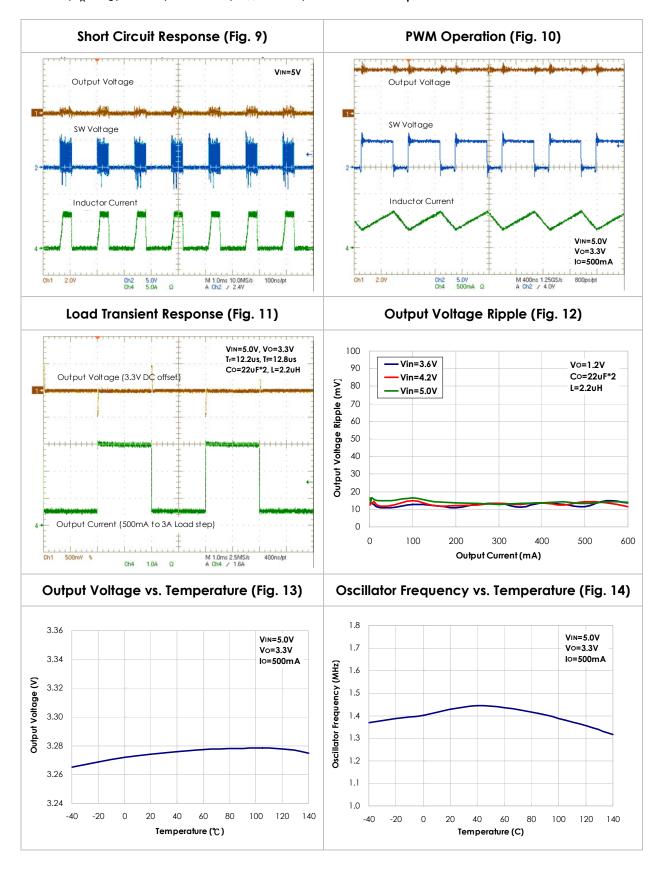
## **Typical Performance Characteristics**

V<sub>IN</sub>=5.0V, T<sub>A</sub>=25°C, L=2.2uH, C<sub>IN</sub>=22uF\*2, C<sub>OUT</sub>=22uF\*2, unless otherwise specified



# **Typical Performance Characteristics**

 $V_{IN}=5.0V$ ,  $T_A=25^{\circ}$ C, L=2.2uH,  $C_{IN}=22uF^*2$ ,  $C_{OUT}=22uF^*2$ , unless otherwise specified.



# **Application Information**

## **Detailed Description**

The EML3173 is a synchronous, step-down DC/DC converter. It allows up to 3.0A current output with adjustable output voltage. EML3173 operates at pure PWM modulation with very small output voltage ripple performance.

During normal operation, the internal oscillator sends a pulse signal to set latch to turn on/off internal high-side MOSFET and low-side MOSFET during each clock cycle. When the current-mode ramp signal which is the sum of internal high-side MOSFET current and slope compensation ramp exceeds output voltage of error amplifier, the PWM comparator will send a signal to reset latch and turn off/on internal high-side MOSFET/low-side MOSFET. The error amplifier adjusts its output voltage by comparing the reference voltage and the feedback voltage.

The basic EML3173 application circuits are shown as in Figure 1, External components selection is determined by the load current and is critical with the selection of inductor and capacitor values.

#### **Power Good**

Power good flag is pulled down when EML3173 start-up and the FB pin voltage is still outside pre-set voltage window. During normal operation phase, when FB pin voltage drop under 87.5% or increase over 112.5%, power good flag is also pulled down.

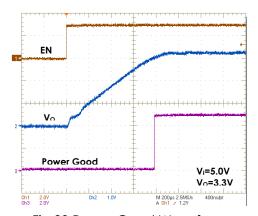


Fig.23 Power Good Waveform

## **Inductor Selection**

The value of the inductor is selected based on the desired ripple current. Large inductance gives low inductor ripple current and small inductance result in high ripple current. However, the larger value inductor has a larger physical size, higher series resistance, and/or lower saturation current. In experience, the value is to allow the peak-to-peak ripple current in the inductor to be 10%~20% maximum load current. The inductance value can be calculated by:

$$L = \frac{\left(V_{IN} - V_{OUT}\right)}{F_{OSC} * \Delta I_L} * \frac{V_{OUT}}{V_{IN}} = \frac{\left(V_{IN} - V_{OUT}\right)}{F_{OSC} * \left(2 * (10\% \sim 20\%) * I_{LOAD}\right)} * \frac{V_{OUT}}{V_{IN}}$$

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The inductor ripple current can be calculated by:

$$\Delta I_{L} = \frac{V_{OUT}}{F_{OSC} * L} * \left( 1 - \frac{V_{OUT}}{V_{IN}} \right)$$

Choose an inductor that does not saturate under the worst-case load conditions, which is the load current plus half the peak-to-peak inductor ripple current, even at the highest operating temperature. The peak inductor current is:

$$I_{L_{-}PEAK} = I_{LOAD} + \frac{\Delta I_{L}}{2}$$

The inductors in different shape and style are available from manufacturers. Shielded inductors are small and radiate less EMI issue. But they cost more than unshielded inductors. The choice depends on EMI requirement, price and size.

#### Recommend Table

Inductor Value (µH)	Dimensions (mm)	Component Supplier	Model	ISAT (A)	DCR (mΩ)
2.2	5.2 x 4.9 x 3.0 max.	CYNTEC	PCMB053T-2R2MS	9	29 typ.
2.2	4.9 x 4.9 x 4.1 typ.	TAIYO YUDEN	NRS5040T2R2NMGJ	5	28.6 typ.

#### **Input Capacitor Selection**

The input capacitor must be connected to the VIN pin and GND pin of EML3173 to maintain steady input voltage and filter out the pulsing input current. The voltage rating of input capacitor must be greater than maximum input voltage plus ripple voltage. In normal operation, the input current is discontinuous in a buck converter. The source current waveform of the high-side MOSFET is a square wave. To prevent large voltage transients, a low ESR input capacitor sized for the maximum RMS current must be used. The RMS value of input capacitor current can be calculated by:

$$\boldsymbol{I}_{\mathit{RMS}} = \boldsymbol{I}_{\mathit{LOAD}\_\mathit{MAX}} * \sqrt{\frac{\boldsymbol{V}_{\mathit{OUT}}}{\boldsymbol{V}_{\mathit{IN}}}} * \left(1 - \frac{\boldsymbol{V}_{\mathit{OUT}}}{\boldsymbol{V}_{\mathit{IN}}}\right)$$

It can be seen that when  $V_O$  is half of  $V_{IN}$ ,  $C_{IN}$  is under the worst current stress. The worst current stress on  $C_{IN}$  is  $I_{O\_MAX}/3.0$  A 47 $\mu$ F ceramic capacitor is recommended value in typical application.

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## **Output Capacitor Selection**

The output capacitor is required to maintain the DC output voltage. Low ESR capacitors are preferred to keep the output voltage ripple low. In a buck converter circuit, output ripple voltage is determined by inductor value, switching frequency, output capacitor value and ESR. The output ripple is determined by:

$$\Delta V_{OUT} = \Delta I_L * \left( ESR_{COUT} + \frac{1}{8 * F_{OSC} * C_{OUT}} \right)$$

Where  $F_{OSC}$  = operating frequency,  $C_{OUT}$ = output capacitance and  $\Delta I_L$  = ripple current in the inductor. For a fixed output voltage, the output ripple is highest at maximum input voltage since  $\Delta I_L$  increases with input voltage. A 22µF ceramic capacitor is recommended value in typical application.

#### Recommend Table

Capacitor Value (µF)	Case Size	Component Supplier	Model
22	0805 1206	TDK	C2012JB0J226M

## **Using Ceramic Input and Output Capacitors**

Care must be taken when ceramic capacitors are used at the input and the output. When a ceramic capacitor is used at the input and the power is supplied by a wall adapter through long wires, a load step at the output can induce ringing at the input, VIN. At best, this ringing can couple to the output and be mistaken as loop instability. At worst, a sudden inrush current through the long wires can potentially cause a voltage spike at V<sub>IN</sub>, which may large enough to damage the part. When choosing the input and output ceramic capacitors, choose the X5R or X7R specification. Their dielectrics have the best temperature and voltage characteristics of all the ceramics for a given value and size.

#### **Load Transient**

A switching regulator typically takes several cycles to respond to the load current step. When a load step occurs, VOUT immediately shifts by an amount equal to

$$\Delta I_{LOAD} * ESR_{COUT}$$

ESR is the effective series resistance of output capacitor.  $\triangle$ ILOAD also begins to charge or discharge Cour generating a feedback error signal used by the regulator to return Vour to its steady-state value. During the recovery time, Vour can be monitored for overshoot or ringing that would indicate a stability problem.

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## **Short-Circuit Protection**

When EML3173 output node is shorted to GND, chip will enter soft-start to protect itself, when short circuit is removed, EML3173 enter normal operation again. If EML3173 reach OCP threshold while short circuit, EML3173 will enter soft-start cycle until the current under OCP threshold.

## **Over Temperature Protection**

The internal high-side MOSFET is turned off when the internal thermal sensor detects that the junction temperature exceeds  $165^{\circ}$ C, entering the Over Temperature Protection mode (OTP). The OTP mode is unlocked at  $130^{\circ}$ C, i.e. a  $35^{\circ}$ C hysteresis.

## **Output Voltage Setting**

The output voltage of EML3173 can be adjusted by a resistive divider according to the following formula:

$$V_{OUT} = V_{REF} * \left(1 + \frac{R_1}{R_2}\right) = 0.8 * \left(1 + \frac{R_1}{R_2}\right)$$

The resistive divider senses the fraction of the output voltage as shown in Fig.24 Using large feedback resistor can increase efficiency, but too large value affects the device's output accuracy because of leakage current going into device's FB pin. The recommended value for R2 is therefore in the range of  $50K\Omega$ .

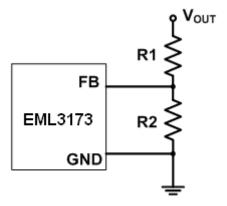


Fig. 24 Setting the Output Voltage

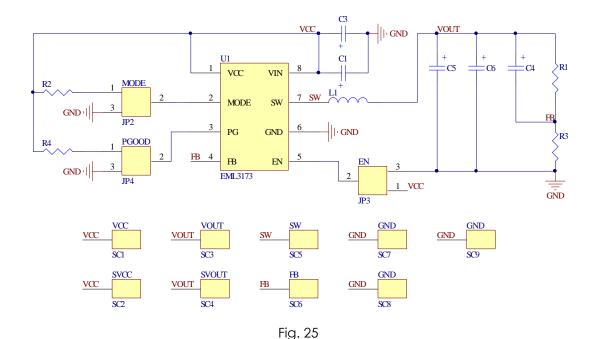
## **Under Voltage Lock Out**

The under-voltage lockout (UVLO) circuitry ensures that the EML3173 starts up with adequate voltage. The regulator output is disabled whenever VIN is below UVLO. The hysteresis of UVLO is designed to be 100 mV.

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# **Applications**

# Typical Schematic for PCB Layout

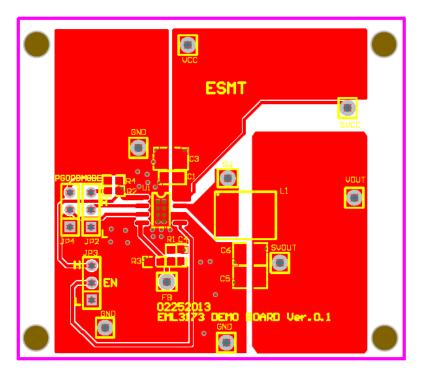


# **PCB Layout Guidelines**

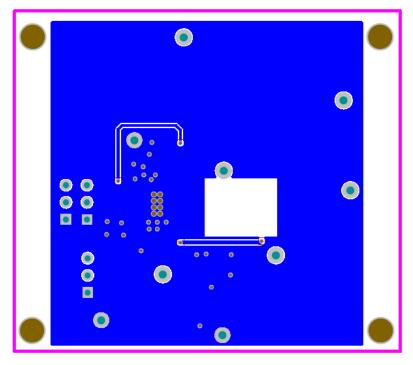
When laying out the printed circuit board, the following checklist should be used to optimize the performance of EML3173.

- 1. The power traces, including the GND trace, the SW trace and the  $V_{\text{IN}}$  trace should be kept direct, short and wide
- 2. Put input capacitor as close as possible to the  $V_{\mbox{\scriptsize IN}}$  and GND pins.
- 3. The FB pin should be connected directly to the feedback resistor divider.
- 4. Keep the switching node, SW, away from the sensitive FB pin and the node should be kept small area.

# Typical Schematic for PCB layout (cont.)

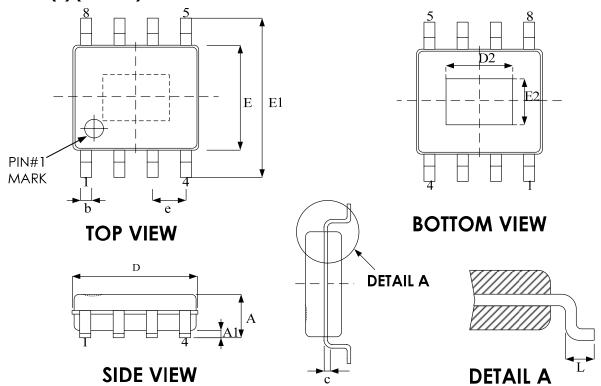


Top Layer



Bottom Layer

# Package Outline Drawing SOP-8 (E) (150 mil)



Crymala o 1	Dimension in mm		
Symbol	Min	Max	
А	1.35	1.75	
A1	0.00	0.25	
Ъ	0.31	0.51	
С	0.10	0.25	
D	4.80	5.00	
Е	3.81	4.00	
E1	5.79	6.20	
е	1.27	BSC	
L	0.40	1.27	

Exposed pad				
	Dimensio	on in mm		
	Min	Max		
D2	2.84	3.30		
E2	2.06	2.41		

# **Revision History**

Revision	Date	Description
1.0	2014.10.23	Initial version.
1.1	2016.11.29	Updated the EN threshold voltage information.
1.2	2017.05.12	Updated Package Outline Drawing

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